



Intermediate Temperature Ceramic Heat Pipe Modeling and Optimization

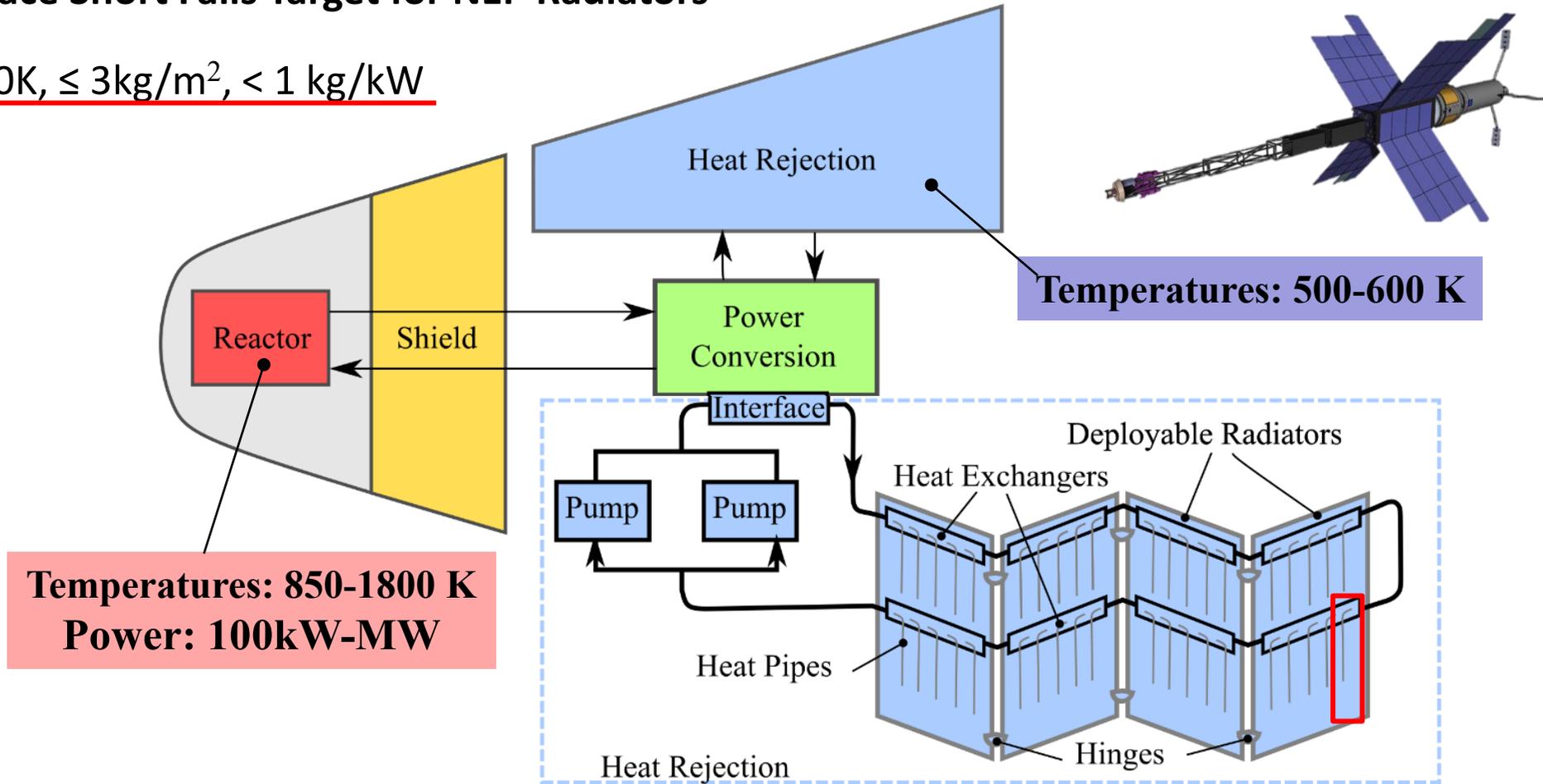
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Presented By
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Cleveland, OH

Civil Space Short Falls Target for NEP Radiators

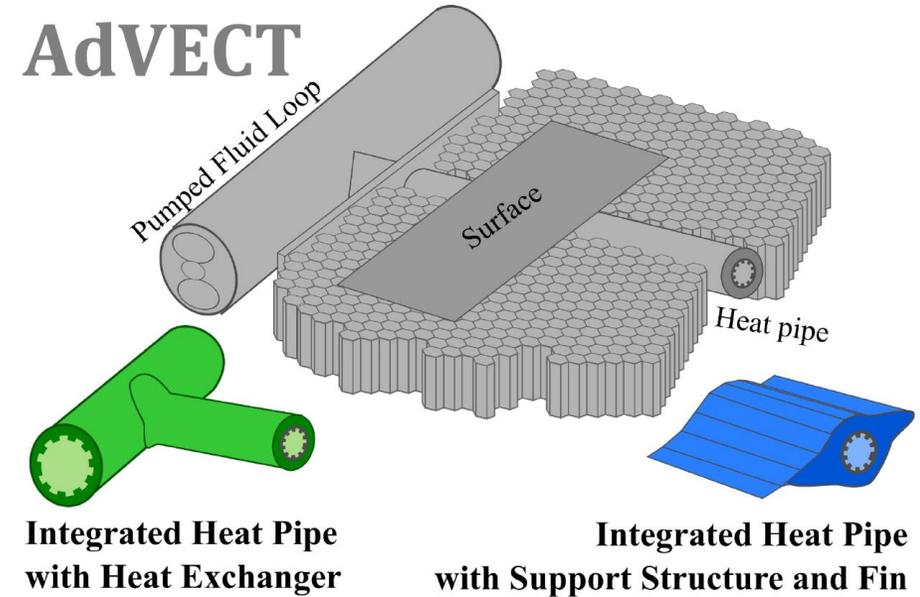
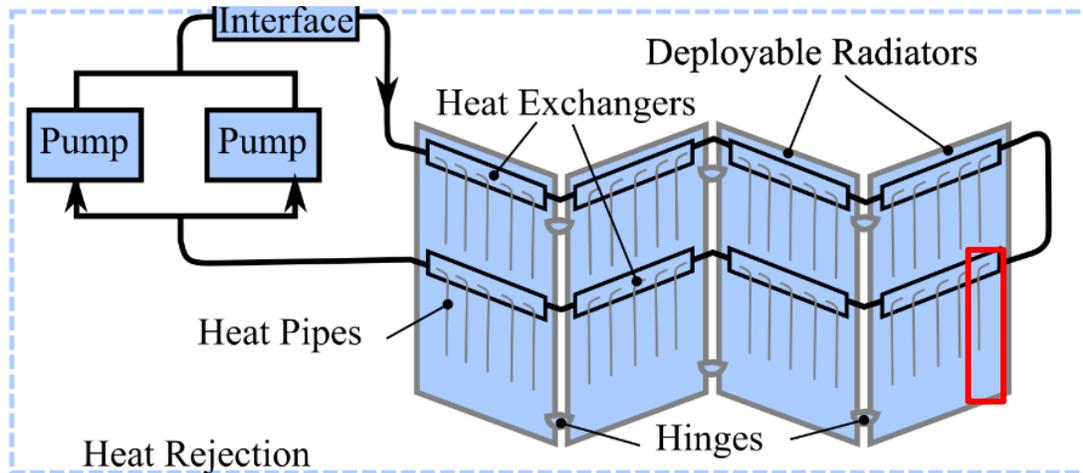
- $>500\text{K}, \leq 3\text{kg}/\text{m}^2, < 1\text{ kg}/\text{kW}$



AdVECT: Additive Vehicle-Embedded Cooling Technologies

Porous Ceramic Radiators with embedded Heat Pipes

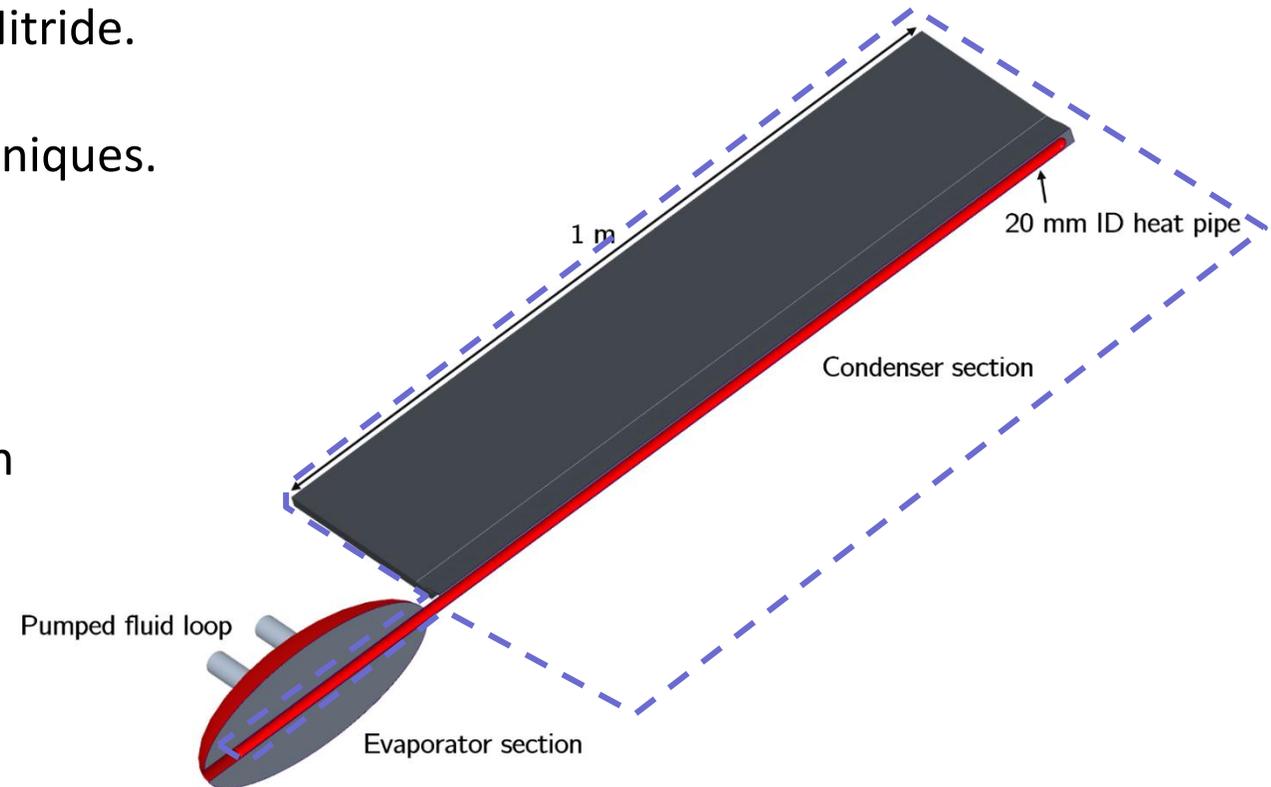
- Operating @ 500-600K
- Areal Density $\leq 2\text{kg/m}^2$
- Specific weight $< 1\text{ kg/kW}$



Approach

- Develop new ceramic resins using Aluminum Nitride.
- Parametric study of printing and sintering techniques.
- Performance testing;
 - Print prototype ceramic heat pipes.
 - Establish feasible, full scale design through simulation.
 - Experimentally validate solutions.

→ Elevate TRL of technology to level 3





Scope



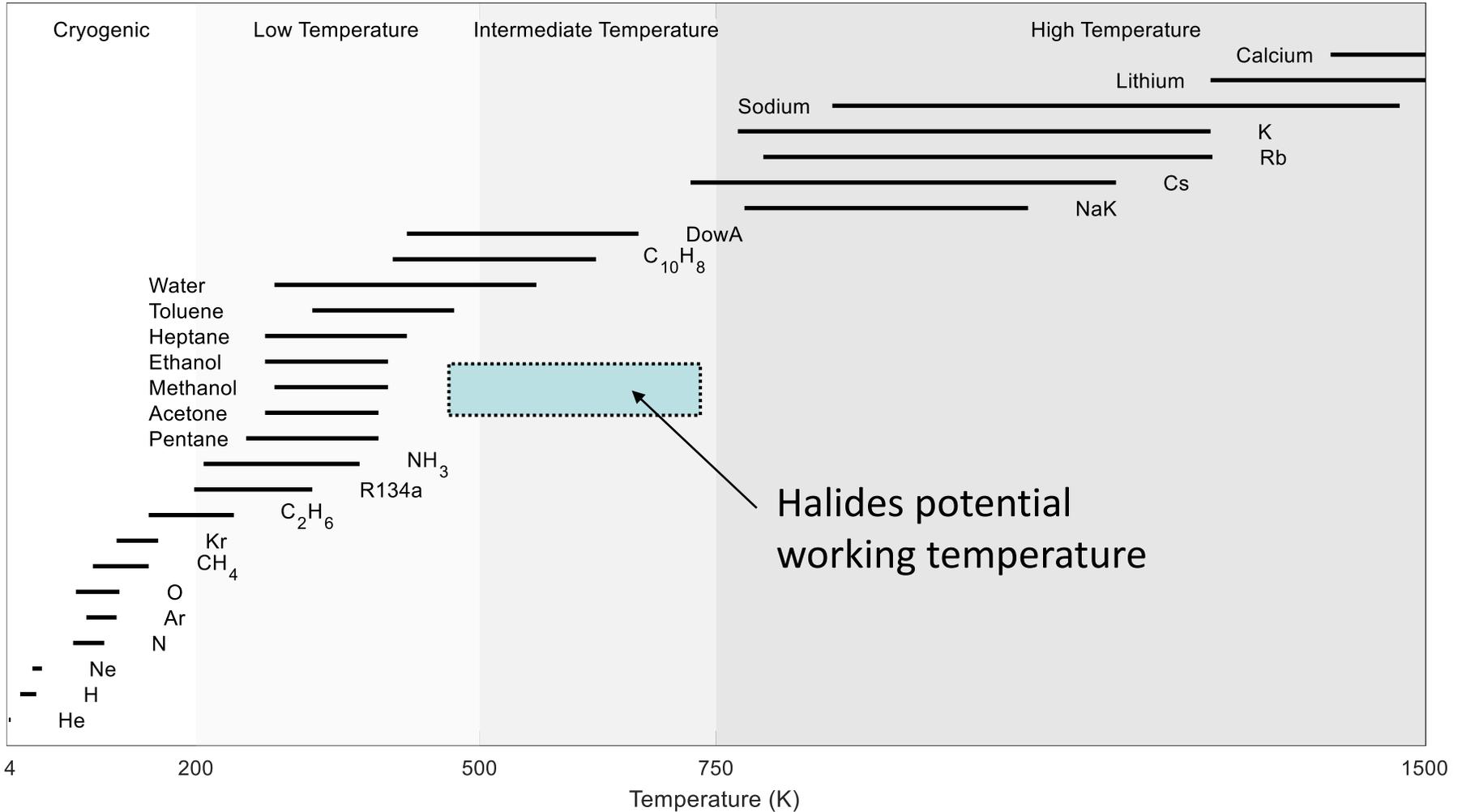
Why ceramics?

Expanded choice of working fluids

+

Novel Form Factors and Topology Optimization

Existing state-of-the-art for heat pipe working fluids

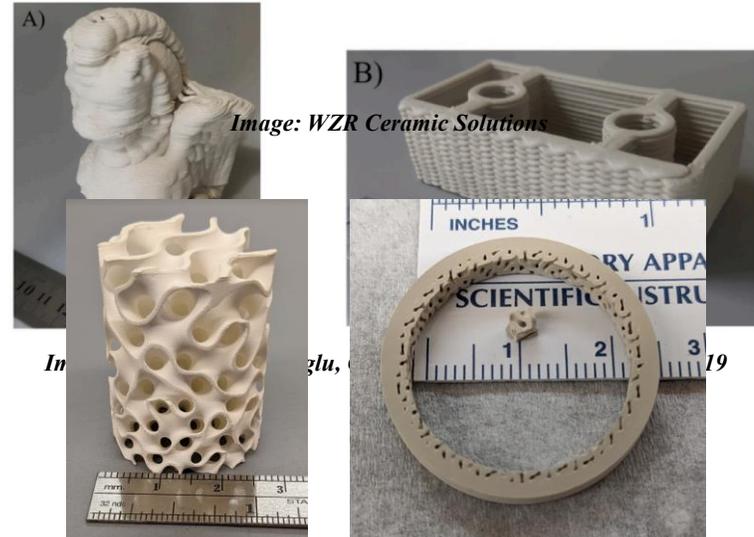
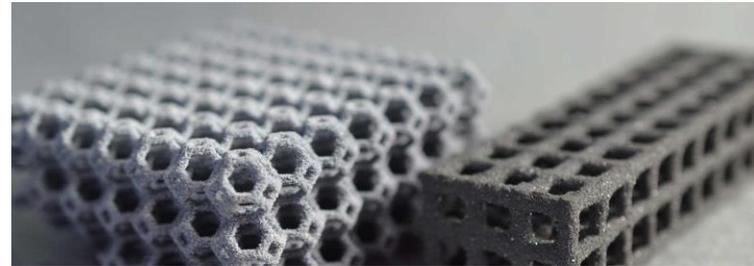


Additively Manufactured Ceramics

- Three primary fabrication methods
 - Binder Jetting
 - Low resolution (50-200 μm layers,
 - Requires large ceramic particles (generally $\geq 50 \mu\text{m}$), porous

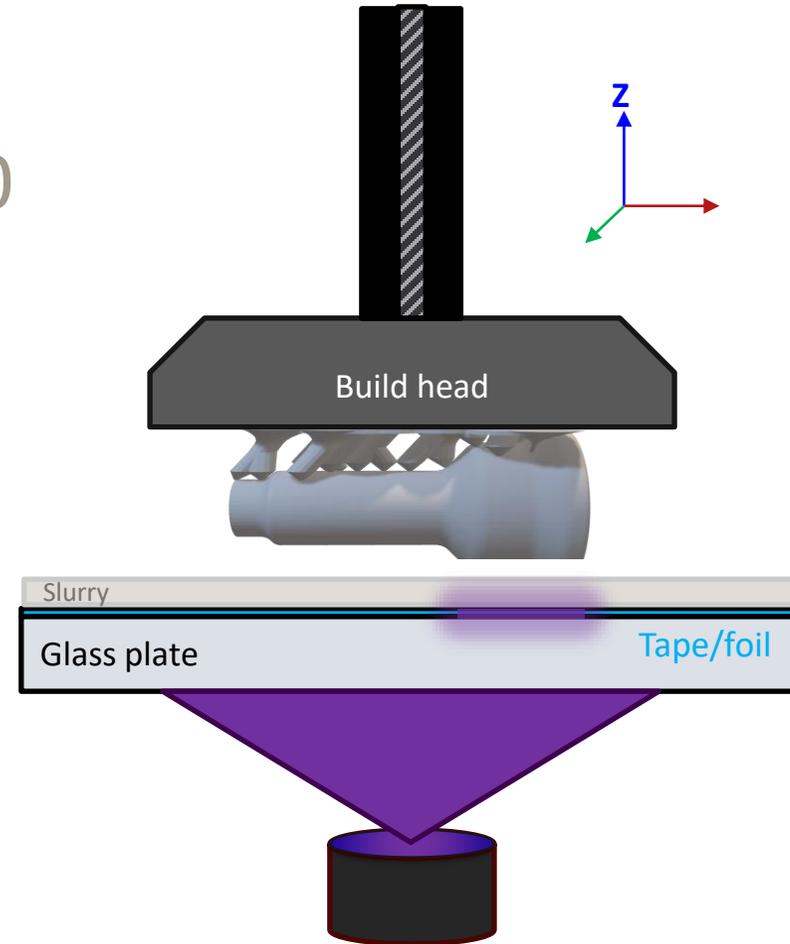
 - Direct Ink Writing
 - Low resolution (minimum feature size tip dependent, generally $> 100 \mu\text{m}$, $> 50 \mu\text{m}$ layer height)
 - Can use small or large ceramic particles

 - Digital Light Processing (DLP)/Stereolithography
 - High resolution ($\leq 50 \mu\text{m}$ minimum feature size, $\leq 50 \mu\text{m}$ layer height)
 - Small ceramic particles ($< 1 \mu\text{m}$)
 - Slurry of photosensitive resin + ceramic



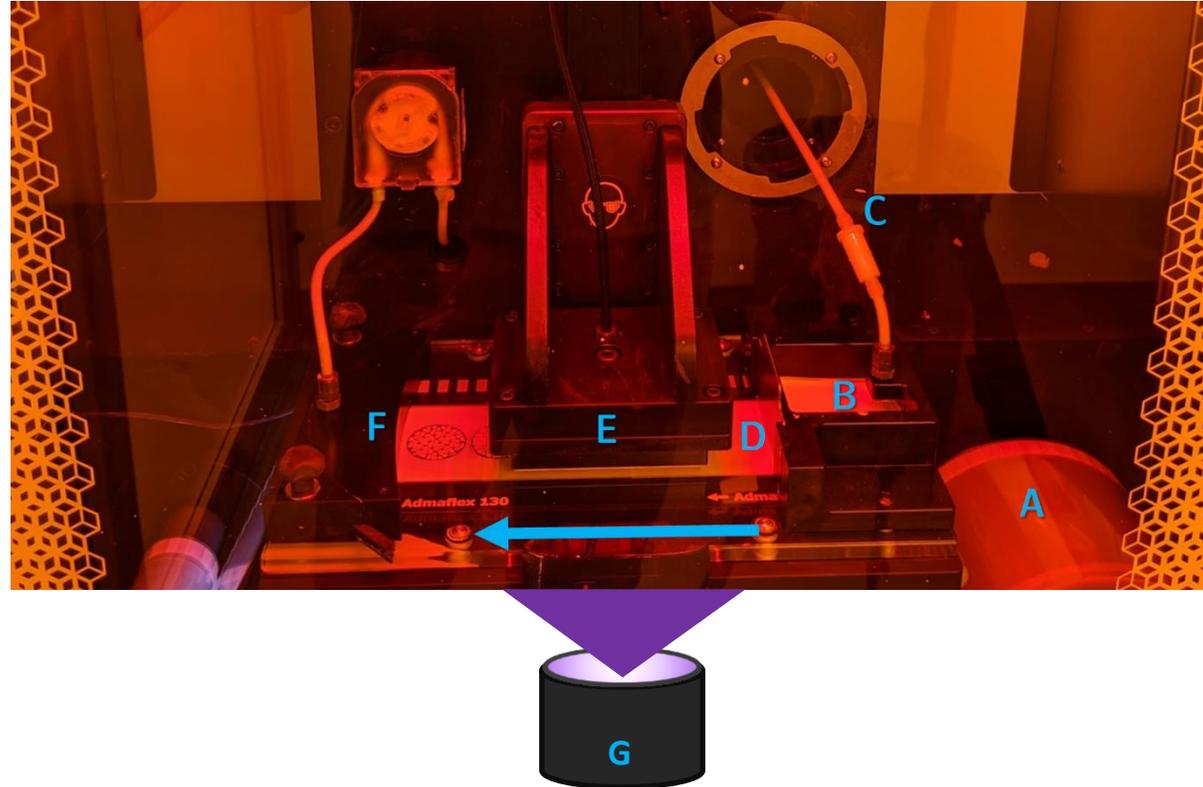
DLP Printing – Admatec A130

- Layerwise printing method
 - 10-50 μm typical
 - 2-5 mm/hr build rate (Z direction)
- 96 x 54 x 110 mm build volume



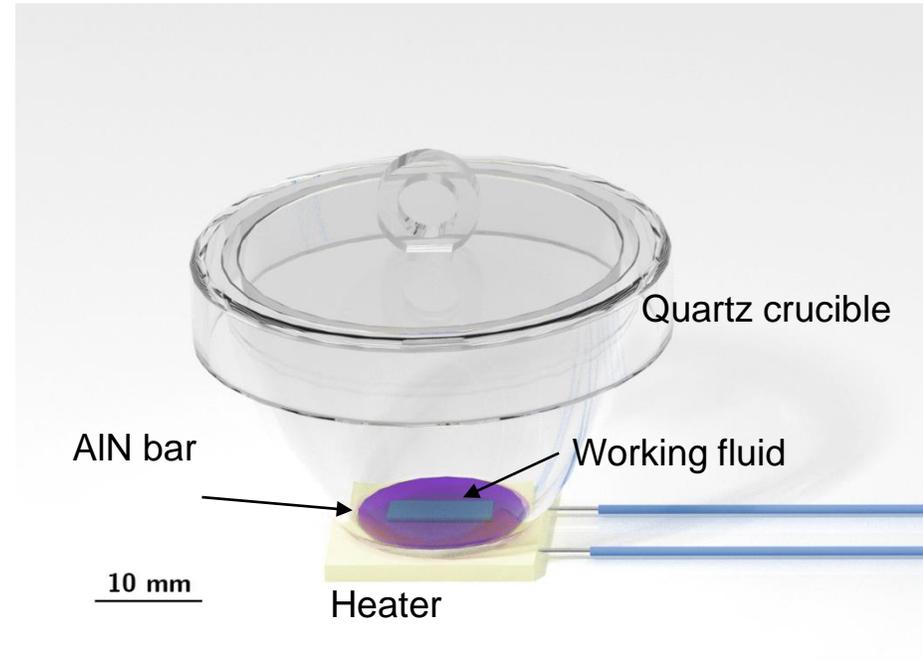
DLP Printing – Admatec A130

- A. Foil roll
- B. Slurry vat
- C. Recirc filter
- D. Doctor blade
- E. Build head
- F. Wiper (recirc)
- G. Projector

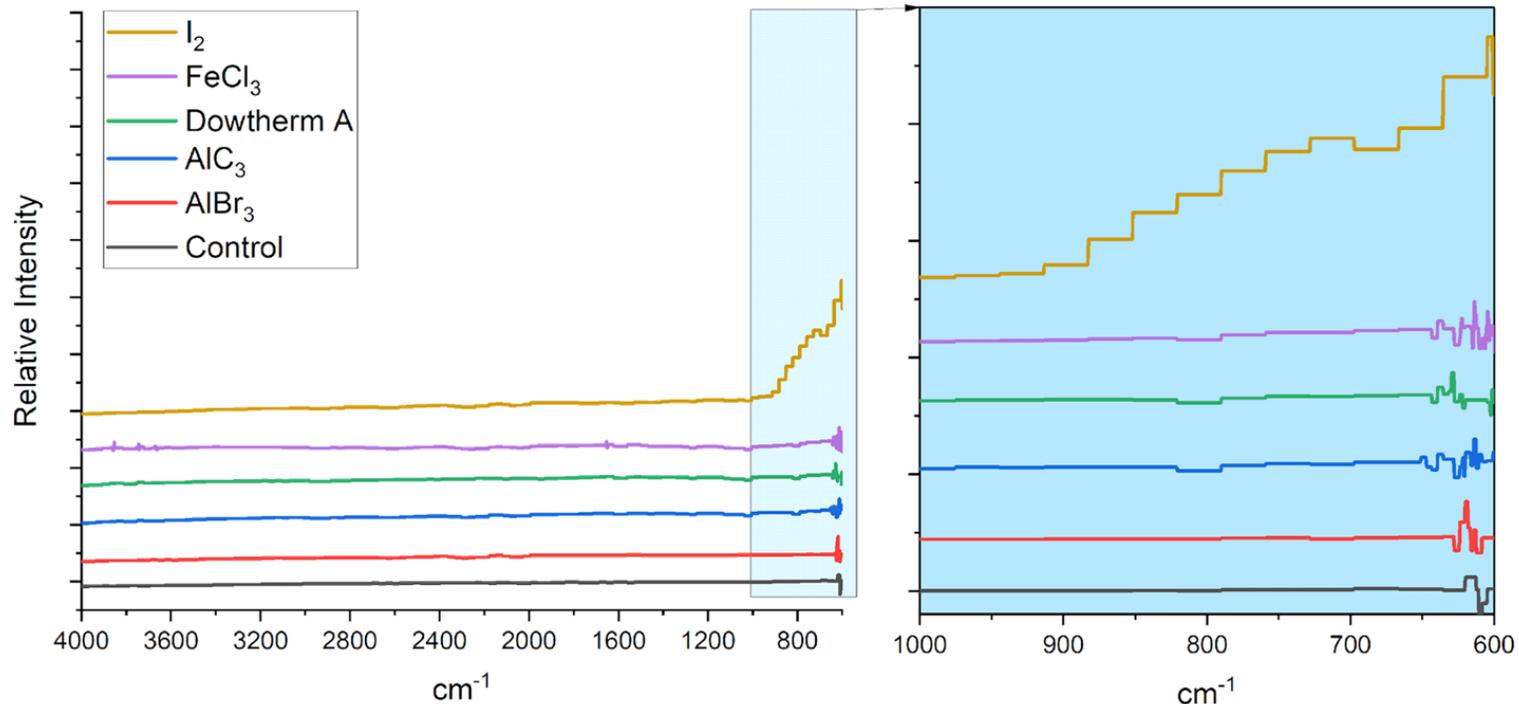


Working Fluid Compatibility Testing

- Fluid heated to melting point in inert atmosphere
- AlN bar immersed
- Fourier transform infrared spectroscopy (FTIR) & SEM after immersion & cleaning



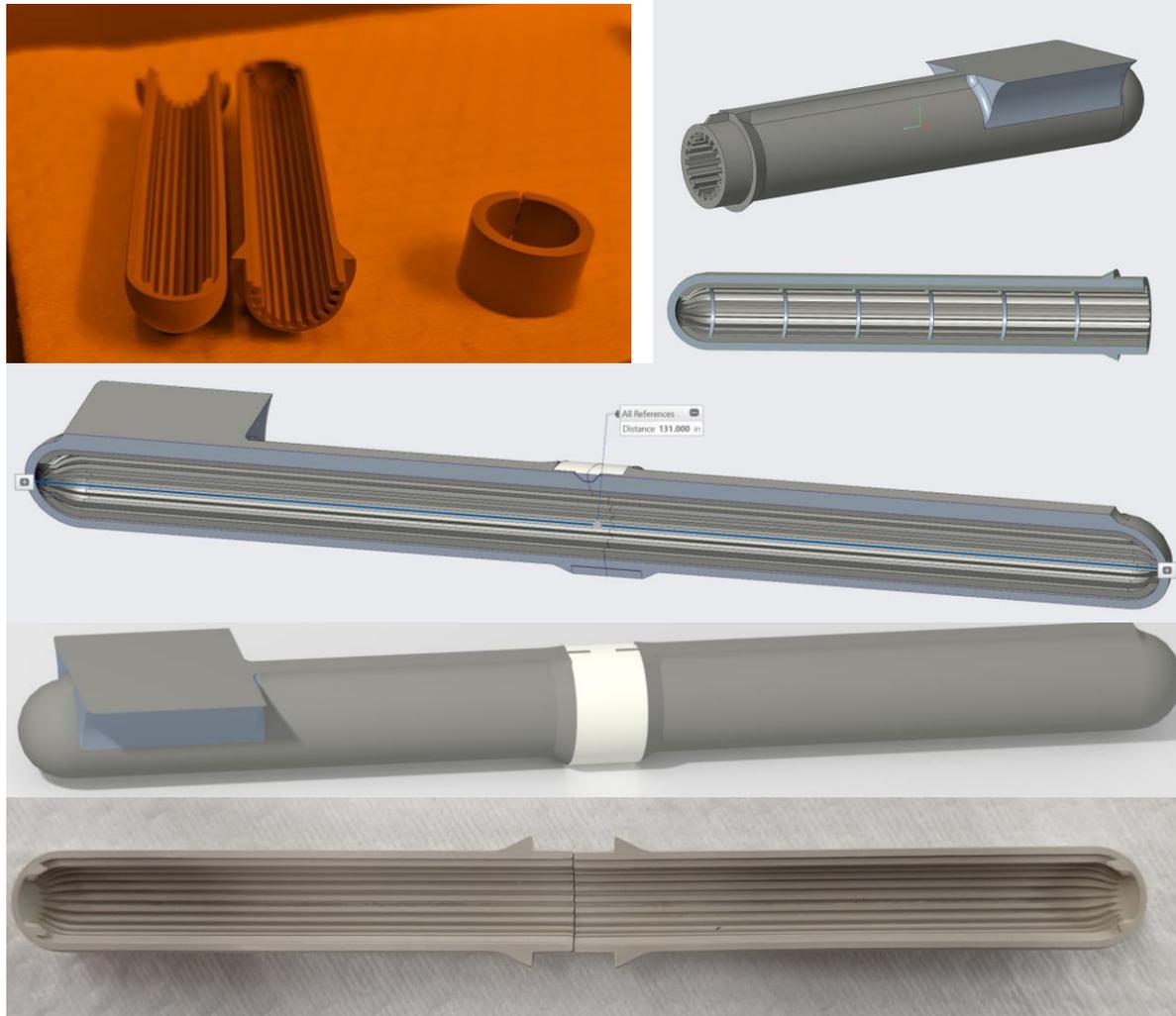
Working Fluid Compatibility Testing



Fourier transform infrared spectroscopy (FTIR)

AdVECT

- Design iteration of grooved heat pipes



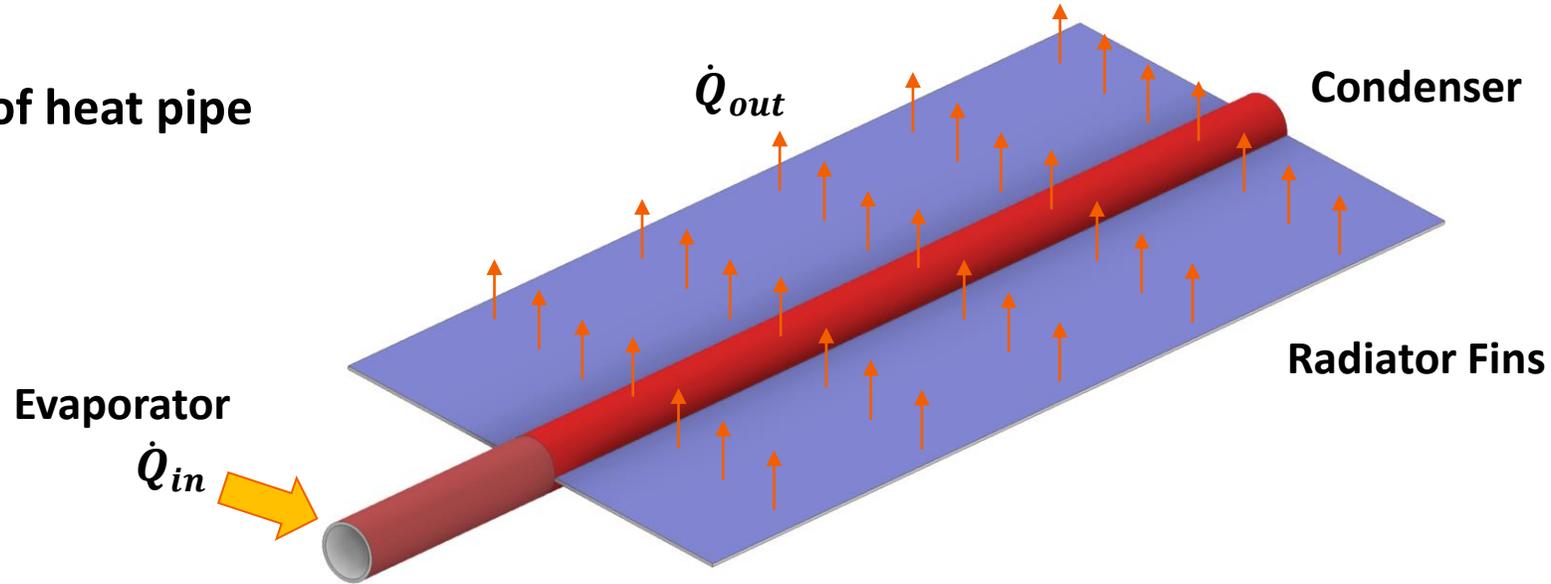


Modeling

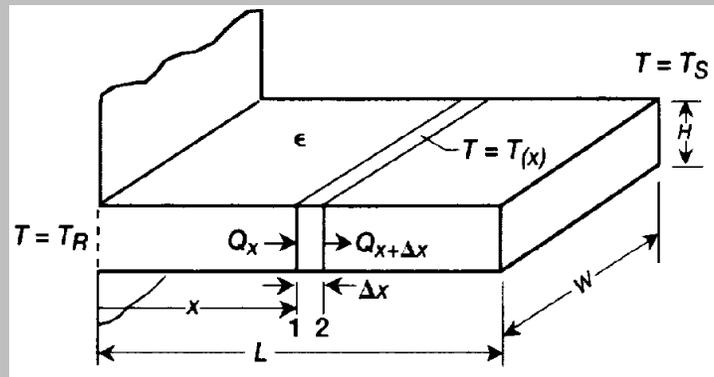


What are the potential benefits to an
Aluminum Nitride-Aluminum Bromide
Embedded Heat Pipe Radiator?
Find out through modeling performance

1D model of heat pipe

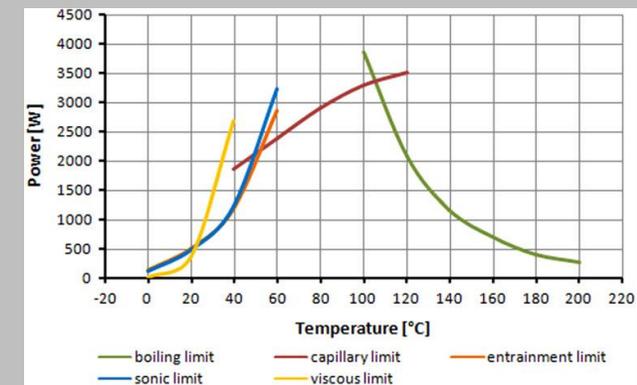


Radiation Model of Fins + HP Surface



$$\dot{Q}_{rad}(T) < \dot{Q}_{env}(T)$$

Performance Limit of Heat Pipe



Performance Limits of Heat Pipes

Capillary Limit

$$\dot{Q}_c = \frac{\rho_l \sigma h_{fg}}{\mu_l} \frac{KA_w}{l_{eff}} \left(\frac{2}{r_{eff}} - \frac{\rho_l g l_t}{\sigma} \cos(\theta) \right)$$

Boiling Limit

$$\dot{Q}_b = \frac{4\pi(l_e)k_{eff}\sigma T_v}{h_{fg}\rho_l \ln\left(\frac{r_s}{r_i}\right)} \left(\frac{1}{r_n} - \frac{1}{r_{eff}} \right)$$

Viscous Limit

$$\dot{Q}_v = \frac{\pi r_i^4 h_{fg} \rho_v P_v}{12 \mu_l l_{eff}}$$

Sonic Limit

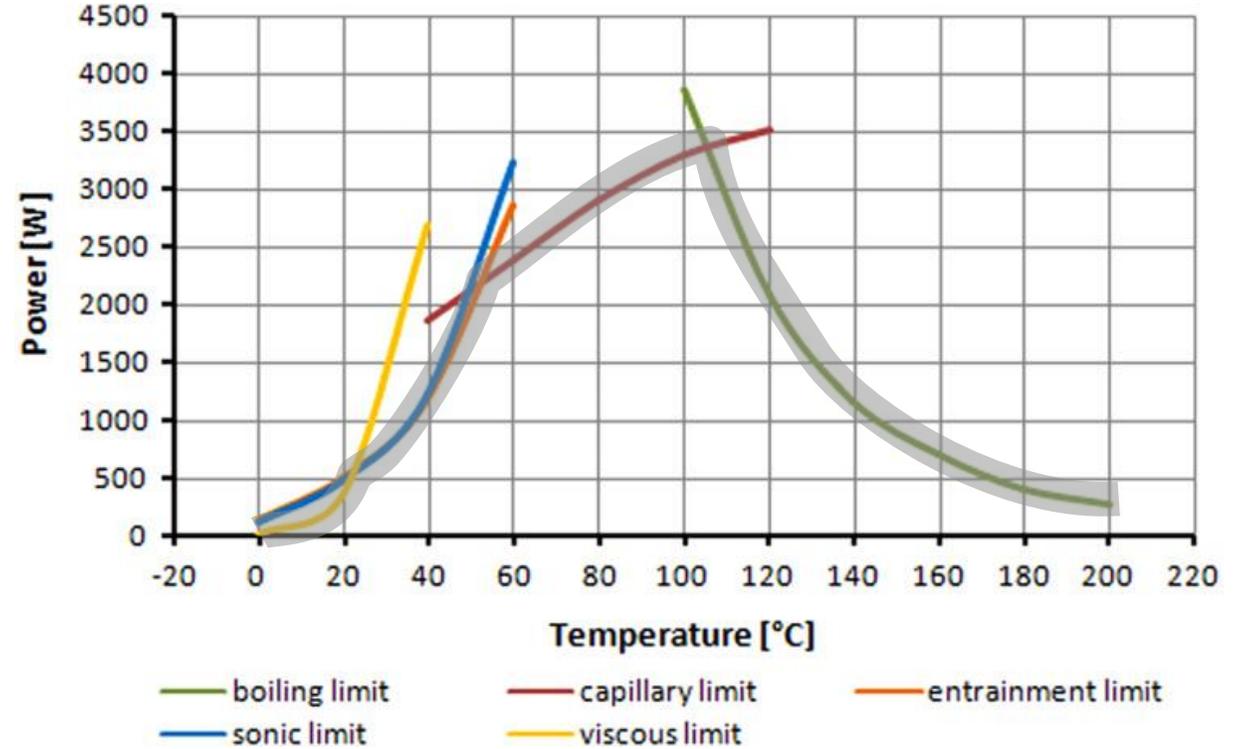
$$\dot{Q}_s = 0.474 A_v h_{fg} (\rho_v P_v)^{0.5}$$

Entrainment Limit

$$\dot{Q}_e = A_v h_{fg} \left(\frac{\rho_v \sigma}{2r_{cav}} \right)^{0.5}$$

Limit Envelope

$$\dot{Q}_{env}(T) = \min(Q_i(T))$$

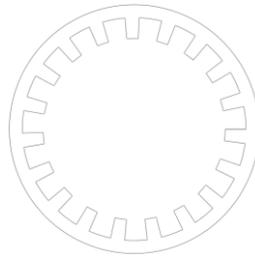


P. Nemeč, A. Čaja, and M. Malcho, "Mathematical model for heat transfer limitations of heat pipe," *Mathematical and Computer Modelling*, vol. 57, no. 1, pp. 126–136, Jan. 2013.

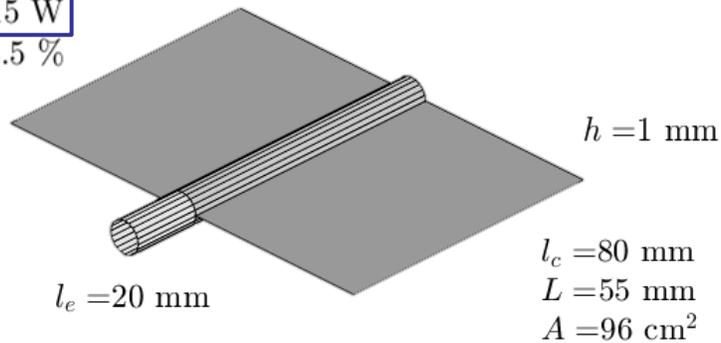
Experimental Scale AlN – Ethanol Heat Pipe

Radii (mm)	Grooves (mm)
$r_o = 4.8$	$w = 0.8$
$r_s = 4.3$	$t = 0.5$
$r_i = 3.5$	$d = 0.8$

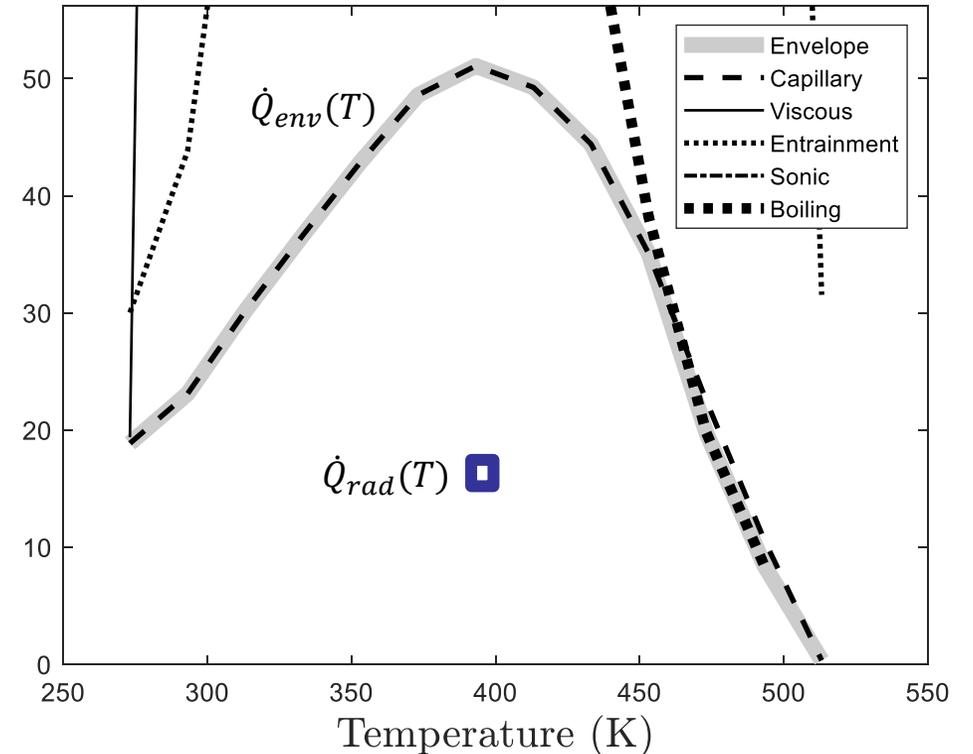
Heat Pipe Performance
 $r_{eff} = 0.79\text{mm}$
 $K = 1520\mu\text{m}^2$
 $k_{eff} = 50\text{W/m}\cdot\text{K}$



$\dot{Q}_{rad} = 15\text{ W}$
 $\eta = 86.5\%$



Performance Limit (W)



Key Performance Metrics

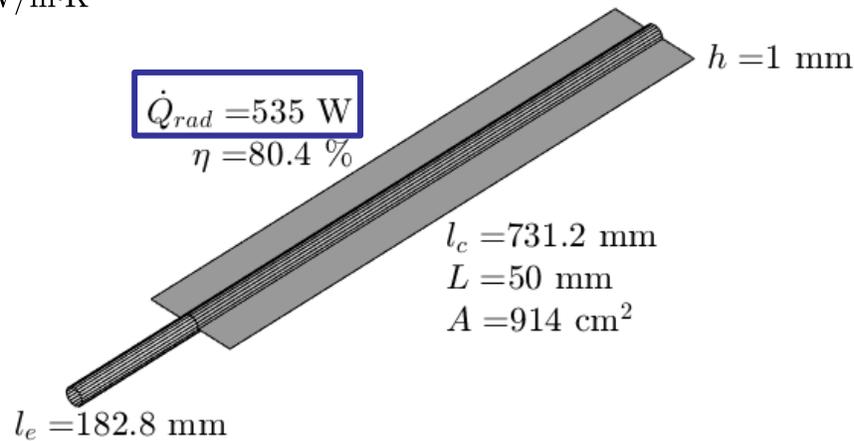
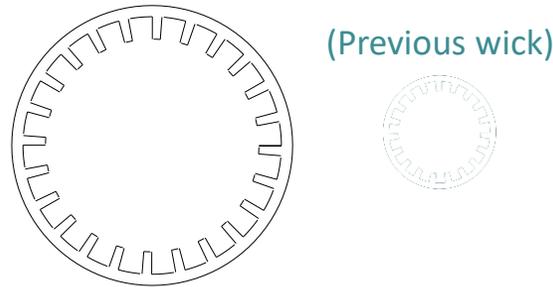
$$m = 38\text{ g}, \frac{A}{m} = 3.9\text{ kg/m}^2, \frac{\dot{Q}}{A} = 1548\text{ W/m}^2, \frac{m}{\dot{Q}} = 2.54\text{ kg/kW}$$

Spacecraft Scale

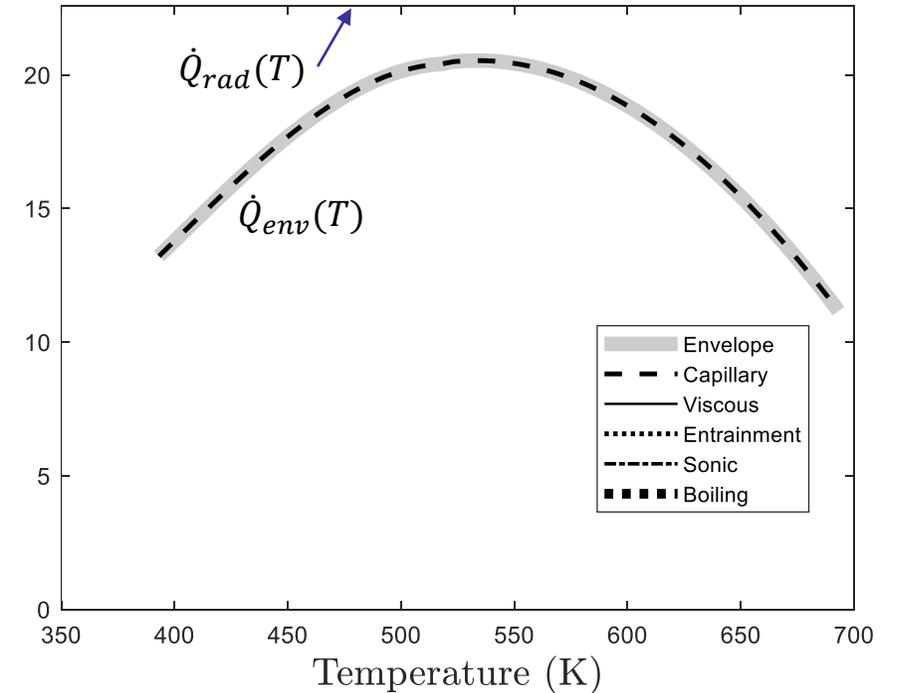
AlN – AlBr₃ (Using geometry without alteration)

Radii (mm)	Grooves (mm)
$r_o = 12.5$	$w = 2$
$r_s = 11.5$	$t = 0.8$
$r_i = 9.5$	$d = 2$

Heat Pipe Performance
 $r_{eff} = 1.96\text{mm}$
 $K = 10868\mu\text{m}^2$
 $k_{eff} = 37\text{W/m}\cdot\text{K}$



Performance Limit (W)

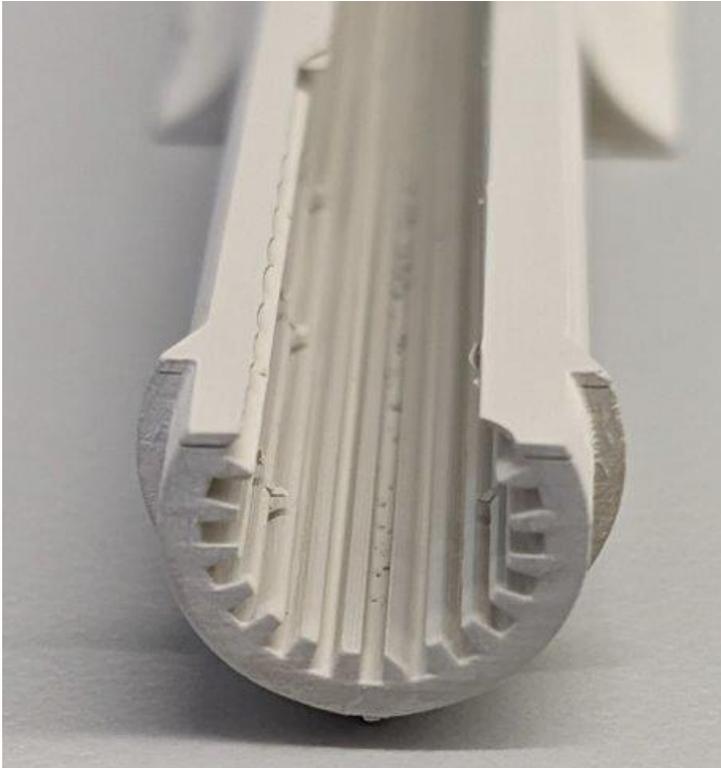


Groove wick cannot meet heat load requirements

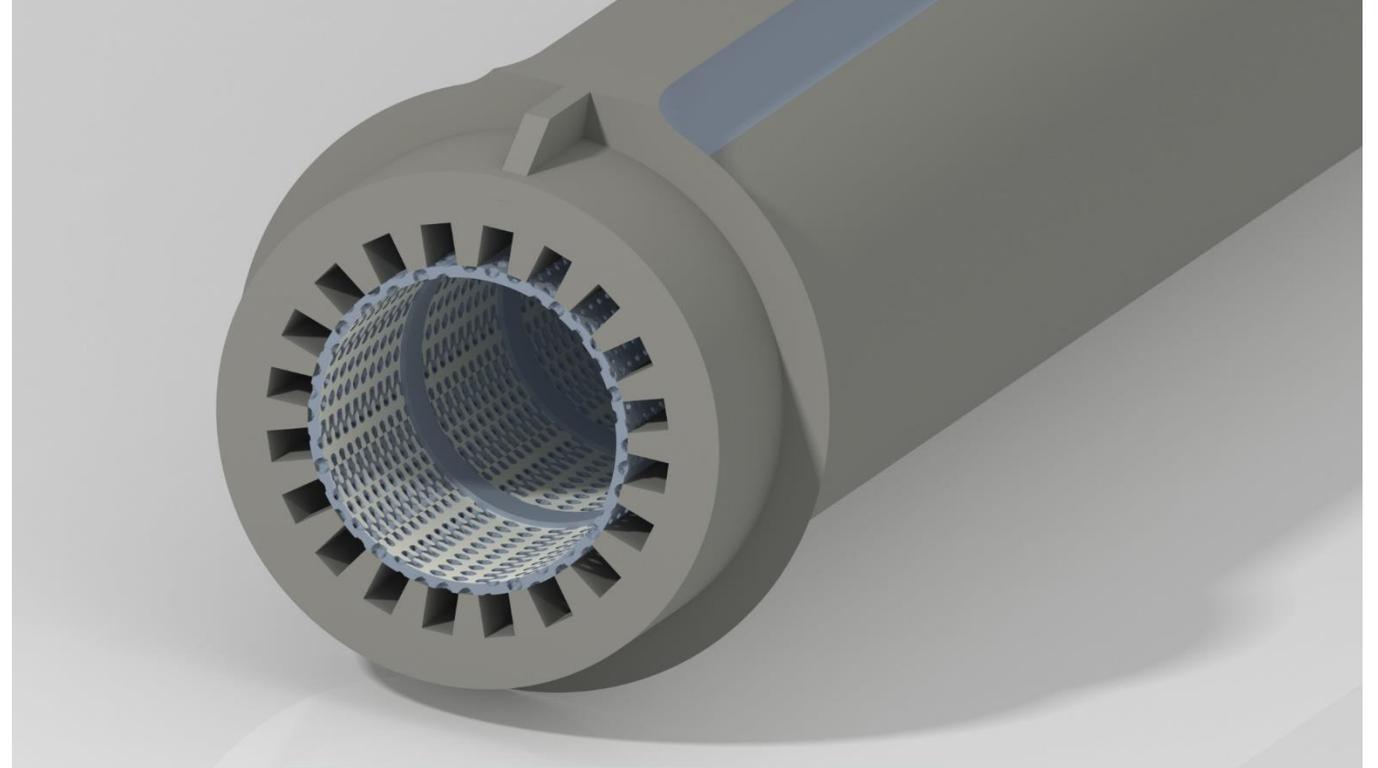
Key Performance Metrics

$$m = 804 \text{ g}, \frac{A}{m} = 8.8 \text{ kg/m}^2, \frac{\dot{Q}}{A} = 5849 \text{ W/m}^2, \frac{m}{\dot{Q}} = 1.5 \text{ kg/kW}$$

New Biporous Groove Design – Mesh Screen Cover (lattice)



Facilitate printing overhanging features



Reduce r_{eff} without significant K losses

Spacecraft Scale

AlN – AlBr₃ (biporous wick)

Radii (mm) Grooves (mm)

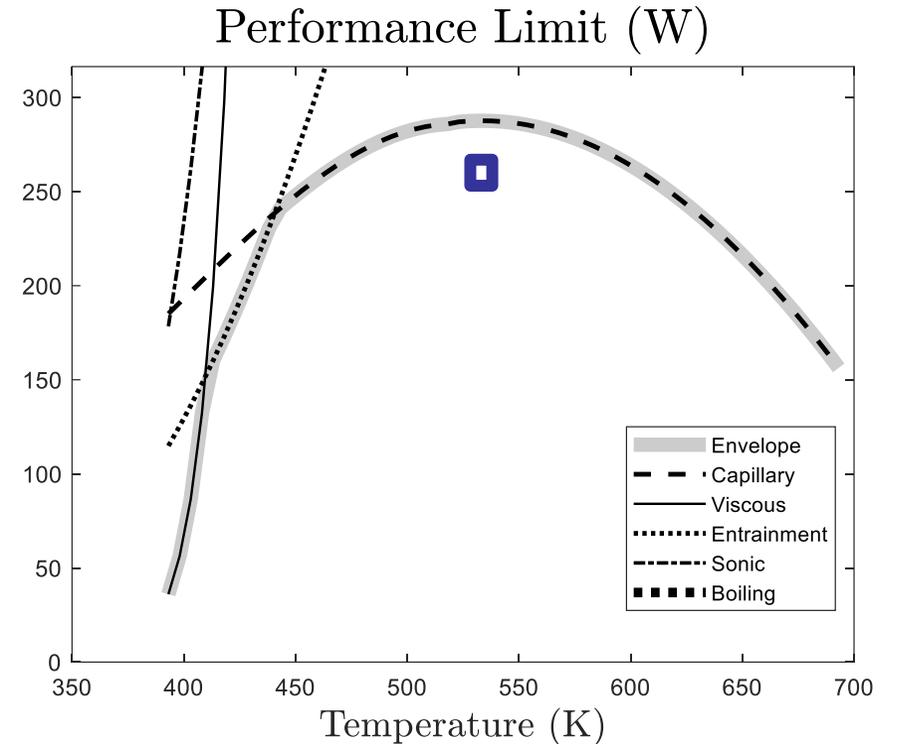
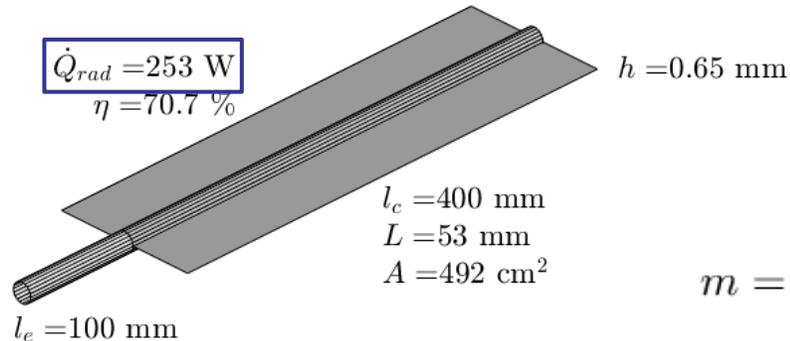
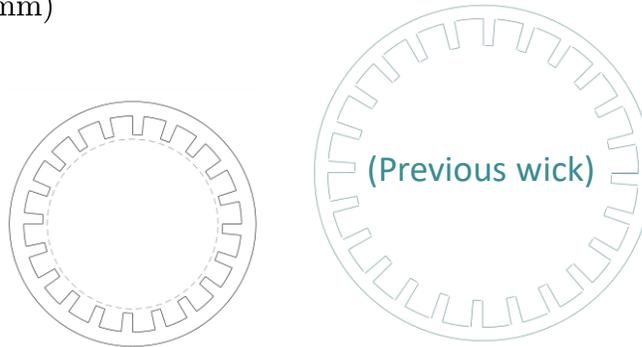
$r_o = 8.5$ $w = 1.4$
 $r_s = 7.5$ $t = 0.7$
 $r_i = 6.2$ $d = 1.3$

Mesh (μm)

$w_m = 50$
 $d_m = 50$

Performance

$r_{eff} = 0.05\text{mm}$ (1.96mm)
 $K = 5013\mu\text{m}^2$ (10868 μm^2)
 $k_{eff} = 43\text{W/m}\cdot\text{K}$ (37W/m.K)



Key Performance Metrics

$$m = 254 \text{ g}, \frac{A}{m} = 5.2 \text{ kg/m}^2, \frac{\dot{Q}}{A} = 5141 \text{ W/m}^2, \frac{m}{\dot{Q}} = 1 \text{ kg/kW}$$

(8.8kg/m²) (1.5kg/kW)



Model Refinement

- Many equations for limits are based on different manufacturing techniques.
 - Use experiments to refine and validate the formulas
- Geometry is not yet optimized for structural strength
 - Use experiments to define yield and stability.
- Geometry uses basic shapes only
 - Explore tapering profiles for radiators and targeted wick structures.
- Only Aluminum Bromide evaluated so far
 - Continue compilation of halide properties to expand model parameters
- Eventually build out COMSOL model for final validation.